

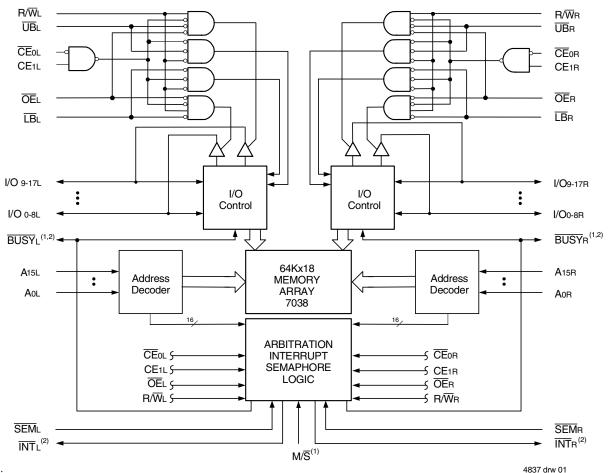
HIGH-SPEED 64K x 18 DUAL-PORT STATIC RAM

Features

- True Dual-Ported memory cells which allow simultaneous reads of the same memory location
- High-speed access
 - Commercial: 15ns (max.)
 - Industrial: 20ns (max.)
- Low-power operation
 - IDT7038LActive: 1W (typ.)Standby: 1mW (typ.)
- Dual chip enables allow for depth expansion without external logic
- IDT7038 easily expands data bus width to 36 bits or more using the Master/Slave select when cascading more than one device

- M/S = VIH for BUSY output flag on Master,
 M/S = VIL for BUSY input on Slave
- Interrupt Flag
- On-chip port arbitration logic
- Full on-chip hardware support of semaphore signaling between ports
- Fully asynchronous operation from either port
- Separate upper-byte and lower-byte controls for multiplexed bus and bus matching compatibility
- TTL-compatible, single 5V (±10%) power supply
- Available in a 100-pin TQFP
- Industrial temperature range (-40°C to +85°C) is available for selected speeds
- Green parts available, see ordering information

Functional Block Diagram



NOTES:

- 1. \overline{BUSY} is an input as a Slave (M/ \overline{S} = V_{IL}) and an output when it is a Master (M/ \overline{S} = V_{IH}).
- 2. BUSY and INT are non-tri-state totem-pole outputs (push-pull).

JUNE 2019

Description

The IDT7038 is a high-speed 64K x 18 Dual-Port Static RAM. The IDT7038 is designed to be used as a stand-alone 1152K-bit Dual-Port RAM or as a combination MASTER/SLAVE Dual-Port RAM for 36-bit-ormore word systems. Using the IDT MASTER/SLAVE Dual-Port RAM approach in 36-bit or wider memory system applications results in full-speed, error-free operation without the need for additional discrete logic.

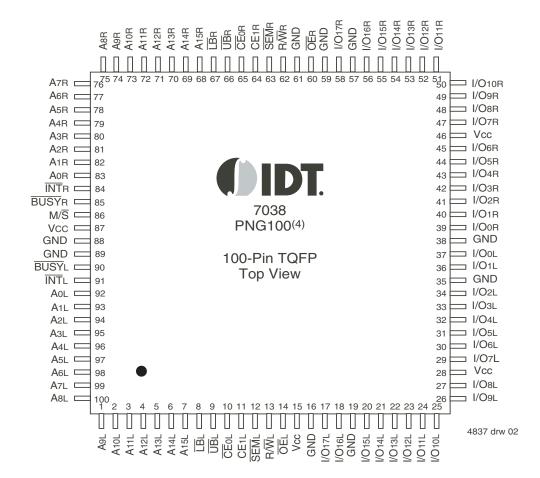
This device provides two independent ports with separate control,

address, and I/O pins that permit independent, asynchronous access for reads or writes to any location in memory. An automatic power down feature controlled by the chip enables (CEo and CE1) permit the on-chip circuitry of each port to enter a very low standby power mode.

Fabricated using CMOS high-performance technology, these devices typically operate on only 1W of power.

The IDT7038 is packaged in a 100-pin Thin Quad Flatpack (TQFP).

Pin Configurations (1,2,3)



- 1. All Vcc pins must be connected to power supply.
- 2. All GND pins must be connected to ground supply.
- 3. Package body is approximately 14mm x 14mm x 1.4mm.
- 4. This package code is used to reference the package diagram.

Pin Names

Left Port	Right Port	Names
CEOL, CE1L	CEOR, CE1R	Chip Enables
R/WL	R/W̄R	Read/Write Enable
ŌĒL	ŌĒR	Output Enable
A0L - A15L	A0R - A15R	Address
I/O0L - I/O17L	I/O0R - I/O17R	Data Input/Output
SEML	SEMR	Semaphore Enable
ŪB∟	Ū B R	Upper Byte Select
<u>LB</u> ∟	ŪBR	Lower Byte Select
ĪNT∟	ĪNTR	Interrupt Flag
BUSYL	BUSYR	Busy Flag
M/S		Master or Slave Select
V	сс	Power
G	ND	Ground

4837 tbl 01

Absolute Maximum Ratings(1)

Symbol	Rating	Commercial & Industrial	Military	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +7.0	-0.5 to +7.0	V
TBIAS	Temperature Under Bias	-55 to +125	-65 to +135	°C
Tstg	Storage Temperature	-65 to +150	-65 to +150	°C
ЮИТ	DC Output Current	50	50	mA

NOTES:

4837 tbl 02

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may
 cause permanent damage to the device. This is a stress rating only and
 functional operation of the device at these or any other conditions above those
 indicated in the operational sections of this specification is not implied. Exposure
 to absolute maximum rating conditions for extended periods may affect
 reliability.
- 2. VTERM must not exceed Vcc + 10% for more than 25% of the cycle time or 10ns maximum, and is limited to \leq 20mA for the period of VTERM \geq Vcc + 10%.

Maximum Operating Temperature and Supply Voltage

Grade	Ambient Temperature ⁽¹⁾	GND	Vcc
Military	-55°C to +125°C	0V	5.0V <u>+</u> 10%
Commercial	0°C to +70°C	0V	5.0V <u>+</u> 10%
Industrial	-40°C to +85°C	0V	5.0V <u>+</u> 10%

NOTES:

1. This is the parameter Ta. This is the "instant on" case temperature.

Recommended DC Operating Conditions

Symbol	Parameter	Min.	Тур.	Max.	Unit
Vcc	Supply Voltage	4.5	5.0	5.5	V
GND	Ground	0	0	0	V
VIH	Input High Voltage	2.2	_	6.0(2)	V
VIL	Input Low Voltage	-0.5 ⁽¹⁾		0.8	V

4837 tbl 04

4837 tbl 05

NOTES:

- 1. $V_{IL} \ge -1.5V$ for pulse width less than 10ns.
- 2. VTERM must not exceed Vcc + 10%.

Capacitance

 $(TA = +25^{\circ}C, f = 1.0MHz)$

Symbol	Parameter ⁽¹⁾	Conditions ⁽²⁾	Max.	Unit
Cin	Input Capacitance	VIN = 3dV	9	pF
Соит	Output Capacitance	Vout = 3dV	10	pF

NOTES:

- This parameter is determined by device characterization but is not production tested.
- 3dV represents the interpolated capacitance when the input and output signals switch from 0V to 3V or from 3V to 0V.

3



Industrial and Commercial Temperature Ranges

Truth Table I: Chip Enable^(1,2)

ΖĒ	<u>C</u> E₀	CE ₁	Mode
	VIL	VIH	Port Selected (TTL Active)
L	<u><</u> 0.2V	≥Vcc -0.2V	Port Selected (CMOS Active)
	VIH	Χ	Port Deselected (TTL Inactive)
	Х	VIL	Port Deselected (TTL Inactive)
Н	≥Vcc -0.2V	Χ	Port Deselected (CMOS Inactive)
	Х	<u><</u> 0.2V	Port Deselected (CMOS Inactive)

4837 tbl 06

NOTES:

- 1. Chip Enable references are shown above with the actual $\overline{\text{CE}}_0$ and CE₁ levels, $\overline{\text{CE}}$ is a reference only.
- 2. 'H' = VIH and 'L' = VIL.
- 3. CMOS standby requires 'X' to be either \leq 0.2V or \geq Vcc 0.2V.

Truth Table II: Non-Contention Read/Write Control

		Inpu	ıts ⁽¹⁾			Outputs		
CE(2)	R/W	ŌĒ	ŪB	<u>ГВ</u>	SEM	I/O ₉₋₁₇	I/O ₀₋₈	Mode
Н	Х	Χ	Х	Х	Н	High-Z	High-Z	Deselected: Power-Down
Х	Х	Х	Н	Н	Н	High-Z	High-Z	Both Bytes Deselected
L	L	Χ	L	Н	Н	DATAIN	High-Z	Write to Upper Byte Only
L	L	Х	Н	L	Н	High-Z	DATAIN	Write to Lower Byte Only
L	L	Х	L	L	Н	DATAIN	DATAIN	Write to Both Bytes
L	Н	L	L	Н	Н	DATAout	High-Z	Read Upper Byte Only
L	Н	L	Н	L	Н	High-Z	DATAout	Read Lower Byte Only
L	Н	L	L	L	Н	DATAout	DATAout	Read Both Bytes
Х	Х	Н	Χ	Χ	Χ	High-Z	High-Z	Outputs Disabled

NOTES:

1. $AOL - A15L \neq AOR - A15R$.

2. Refer to Chip Enable Truth Table.

Truth Table III: Semaphore Read/Write Control⁽¹⁾

		Inpu	ıts ⁽¹⁾			Outputs		
$\overline{CE^{(2)}}$	R/W	ŌĒ	ŪB	ĪΒ	SEM	I/O ₉₋₁₇	I/O ₀₋₈	Mode
Н	Н	L	Х	Х	L	DATAout	DATAout	Read Data in Semaphore Flag
Х	Н	L	Н	Н	L	DATAout	DATAout	Read Data in Semaphore Flag
Н	↑	Х	Х	Х	L	DATAIN	DATAIN	Write I/Oo into Semaphore Flag
Х	↑	Χ	Н	Н	L	DATAIN	DATAIN	Write I/Oo into Semaphore Flag
L	Х	Χ	L	Х	L			Not Allowed
L	Х	Х	Х	L	L			Not Allowed

4837 tbl 08

4837 drw 07

- 1. There are eight semaphore flags written to via I/Oo and read from all the I/Os (I/Oo-I/O17). These eight semaphore flags are addressed by Ao-A2.
- 2. Refer to Chip Enable Truth Table.



Industrial and Commercial Temperature Ranges

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range⁽²⁾ ($Vcc = 5.0V \pm 10\%$)

			7038L		
Symbol	Parameter	Test Conditions	Min.	Max.	Unit
Iu	Input Leakage Current ⁽¹⁾	Vcc = 5.5V, Vℕ = 0V to Vcc		5	μΑ
llo	Output Leakage Current	\overline{CE} = ViH, Vout = 0V to Vcc	-	5	μΑ
Vol	Output Low Voltage	IoL = 4mA	-	0.4	V
Vон	Output High Voltage	IOH = -4mA	2.4	_	V

4837 tbl 09

NOTES:

- 1. At Vcc ≤ 2.0V, input leakages are undefined.
- 2. Refer to Chip Enable Truth Table.

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range⁽¹⁾ ($Vcc = 5.0V \pm 10\%$)

					7038L15 Com'l Only		8L20 & Ind	
Symbol	Parameter	Test Condition	Version	Typ. ⁽¹⁾	Max	Typ. ⁽¹⁾ Max		Unit
lcc	Dynamic Operating Current	<u>CE</u> = V _I L, Outputs Disabled <u>SEM</u> = V _I H	COM'L L	220	340	200	300	mA
	(Both Ports Active)	$f = f_{MAX}^{(2)}$	IND L	_		200	360	
ISB1	Standby Current (Both Ports - TTL Level	<u>CEL</u> = <u>CER</u> = VIH <u>SEM</u> R = <u>SEM</u> L = VIH	COM'L L	65	100	50	75	mA
	Inputs)	$f = f_{MAX}^{(2)}$	IND L	_	_	50	120	
ISB2	Standby Current (One Port - TTL Level	CE"A" = VIL and CE"B" = VIH(4)	COM'L L	145	225	130	195	mA
	Inputs)	Active Port Outputs Disabled, f=fmax ⁽²⁾ , SEMR = SEML = VIH	IND L	_		130	235	
ISB3	Full Standby Current	Both Ports CEL and	COM'L L	0.2	3.0	0.2	3.0	mA
	(Both Ports - All CMOS Level Inputs)	$\overline{\text{CEr}} \ge \text{Vcc} - 0.2\text{V}, \ \text{Vin} \ge \text{Vcc} - 0.2\text{V}$ $\underline{\text{or}} \ \text{Vin} \le 0.2\text{V}, \ f = 0^{(3)}$ $\underline{\text{SEMr}} = \overline{\text{SEML}} \ge \text{Vcc} - 0.2\text{V}$	IND L			0.2	3.0	
ISB4	Full Standby Current (One Port - All CMOS Level Inputs)	$\overline{CE}^{A^*} \leq 0.2V$ and $\overline{CE}^{B^*} \geq Vcc - 0.2V^{(4)}$	COM'L L	135	220	120	190	mA
	Level Inpuis)	SEMR = SEML \geq Vcc - 0.2V, Vin \geq Vcc - 0.2V or Vin \leq 0.2V, Active Port Outputs Disabled, f = fmax ⁽²⁾	IND L	_	_	120	230	

- 1. Vcc = 5V, TA = +25°C, and are not production tested. Iccdc = 120mA (Typ.)
- 2. At f = fmax, address and control lines (except Output Enable) are cycling at the maximum frequency read cycle of 1/ tRc, and using "AC Test Conditions" of input levels of GND to 3V.
- 3. f = 0 means no address or control lines change.
- 4. Port "A" may be either left or right port. Port "B" is the opposite from port "A".
- 5. Refer to Chip Enable Truth Table.



Industrial and Commercial Temperature Ranges

AC Test Conditions

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns Max.
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	Figures 1 and 2
	4837 tbl 11

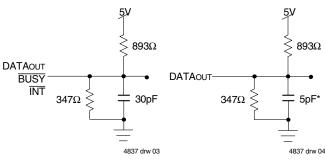
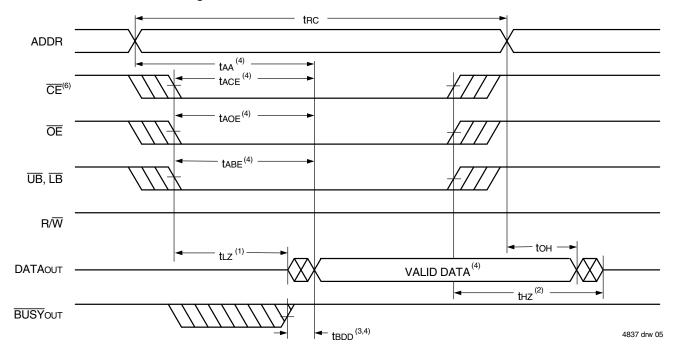


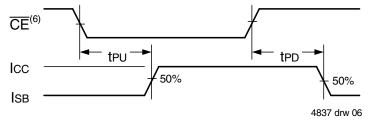
Figure 1. AC Output Test Load

Figure 2. Output Test Load (for tLz, tHz, twz, tow) * Including scope and jig.

Waveform of Read Cycles⁽⁵⁾



Timing of Power-Up Power-Down



- 1. Timing depends on which signal is asserted last, \overline{OE} , \overline{CE} , \overline{LB} or \overline{UB} .
- 2. Timing depends on which signal is de-asserted first \overline{CE} , \overline{OE} , \overline{LB} or \overline{UB} .
- 3. tbbb delay is required only in cases where the opposite port is completing a write operation to the same address location. For simultaneous read operations BUSY has no relation to valid output data.
- 4. Start of valid data depends on which timing becomes effective last tage, tage, tage or tbdd.
- 5. $\overline{SEM} = VIH.$
- 6. Refer to Chip Enable Truth Table.

AC Electrical Characteristics Over the

Operating Temperature and Supply Voltage Range

		7038L1 Com'l O				
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
READ CYCLE						
trc	Read Cycle Time	15		20	_	ns
taa	Address Access Time	_	15	_	20	ns
tace	Chip Enable Access Time ⁽⁴⁾	_	15	_	20	ns
taoe	Output Enable Access Time	_	10	_	12	ns
tон	Output Hold from Address Change	3	_	3	_	ns
tLZ.	Output Low-Z Time ^(1,2)	3	_	3	_	ns
tHZ	Output High-Z Time ^(1,2)	_	10	_	10	ns
tru	Chip Enable to Power Up Time (2)	0	_	0	_	ns
tPD	Chip Disable to Power Down Time ⁽²⁾	_	15	_	20	ns
tsop	Semaphore Flag Update Pulse (OE or SEM)	10		10	_	ns
tsaa	Semaphore Address Access Time	_	15		20	ns

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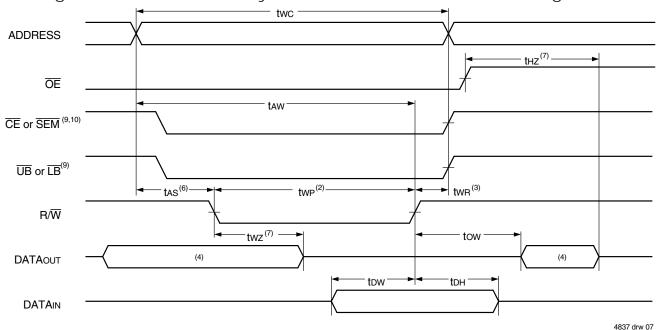
AC Electrical Characteristics Over the Operating Temperature and Supply Voltage

			7038L15 Com'l Only		7038L20 Com'l & Ind	
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
WRITE CYCLE						
twc	Write Cycle Time	15	_	20	_	ns
tew	Chip Enable to End-of-Write ⁽³⁾	12	_	15	_	ns
taw	Address Valid to End-of-Write	12	_	15		ns
tas	Address Set-up Time ⁽³⁾	0		0		ns
twp	Write Pulse Width	12	_	15	_	ns
twr	Write Recovery Time	0		0		ns
tow	Data Valid to End-of-Write	10		15		ns
tHZ	Output High-Z Time ^(1,2)	_	10		10	ns
tон	Data Hold Time ⁽⁴⁾	0		0		ns
twz	Write Enable to Output in High-Z ^(1,2)		10		10	ns
tow	Output Active from End-of-Write ^(1,2,4)	0	_	0		ns
tswrd	SEM Flag Write to Read Time	5		5	_	ns
tsps	SEM Flag Contention Window	5	_	5	_	ns

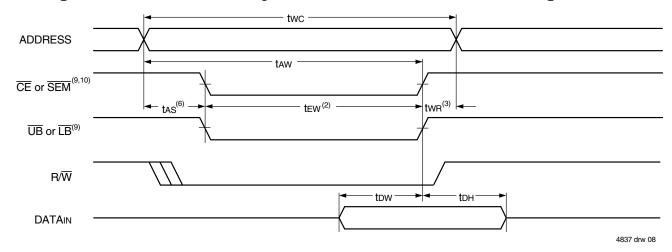
NOTES

- 1. Transition is measured 0mV from Low or High-impedance voltage with Output Test Load (Figure 2).
- $2. \quad \text{This parameter is } \underline{\text{guara}} \underline{\text{nteed by }} \underline{\text{device}} \underline{\text{characterization}}, \underline{\text{but is not production}} \underline{\text{tested}}.$
- 3. To access RAM, $\overline{\text{CE}}=\text{VIL}$ and $\overline{\text{SEM}}=\text{ViH}$. To access semaphore, $\overline{\text{CE}}=\text{ViH}$ and $\overline{\text{SEM}}=\text{ViL}$. Either condition must be valid for the entire tew time.
- 4. The specification for tDH must be met by the device supplying write data to the RAM under all operating conditions. Although tDH and tow values will vary over voltage and temperature, the actual tDH will always be smaller than the actual tow.

Timing Waveform of Write Cycle No. 1, R/W Controlled Timing (1,5,8)



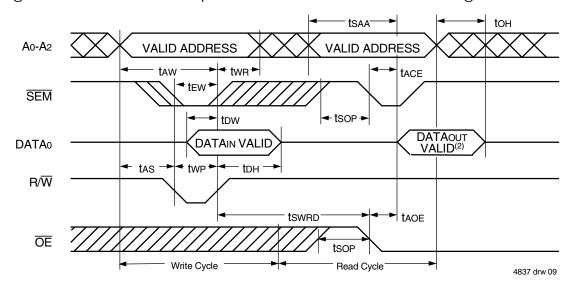
Timing Waveform of Write Cycle No. 2, **CE** Controlled Timing^(1,5)



- 1. R/\overline{W} or \overline{CE} or \overline{UB} and \overline{LB} = ViH during all address transitions.
- 2. A write occurs during the overlap (tew or twp) of a $\overline{CE} = V_{IL}$ and a R/ $\overline{W} = V_{IL}$ for memory array writing cycle. 3. twn is measured from the earlier of \overline{CE} or R/ \overline{W} (or \overline{SEM} or R/ \overline{W}) going HIGH to the end of write cycle.
- 4. During this period, the I/O pins are in the output state and input signals must not be applied.
- 5. If the $\overline{\text{CE}}$ or $\overline{\text{SEM}} = \text{VIL}$ transition occurs simultaneously with or after the $\overline{\text{RW}} = \text{VIL}$ transition, the outputs remain in the High-impedance state.
- 6. Timing depends on which enable signal is asserted last, $\overline{\text{CE}}$ or $R\overline{W}$.
- 7. This parameter is guaranteed by device characterization, but is not production tested. Transition is measured 0mV from steady state with the Output Test Load
- 8. If $\overline{OE} = V_{IL}$ during R/W controlled write cycle, the write pulse width must be the larger of twp or (twz + tow) to allow the I/O drivers to turn off and data to be placed on the bus for the required tow. If $\overrightarrow{OE} = VIH$ during an R/\overline{W} controlled write cycle, this requirement does not apply and the write pulse can be as short as the
- 9. To access RAM, $\overline{\text{CE}} = \text{VIL}$ and $\overline{\text{SEM}} = \text{VIH}$. To access semaphore, $\overline{\text{CE}} = \text{VIH}$ and $\overline{\text{SEM}} = \text{VIL}$. Lew must be met for either condition.
- 10. Refer to Chip Enable Truth Table.



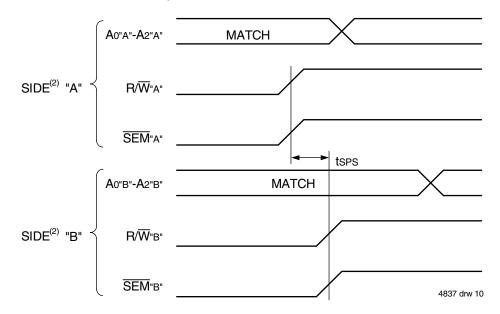
Timing Waveform of Semaphore Read after Write Timing, Either Side(1)



NOTES:

- 1. $\overline{\text{CE}} = \text{ViH}$ or $\overline{\text{UB}}$ and $\overline{\text{LB}} = \text{ViH}$ for the duration of the above timing (both write and read cycle) (Refer to Chip Enable Truth Table).
- 2. "DATAOUT VALID" represents all I/O's (I/Oo I/O17) equal to the semaphore value.

Timing Waveform of Semaphore Write Contention (1,3,4)



- 1. $DOR = DOL = VIL, \overline{CE}L = \overline{CE}R = VIH, or both \overline{UB} and \overline{LB} = VIH (Refer to Chip Enable Truth Table).$
- 2. All timing is the same for left and right ports. Port "A" may be either left or right port. "B" is the opposite from port "A".
- 3. This parameter is measured from R/W"A" or SEM"A" going HIGH to R/W"B" or SEM"B" going HIGH.
- 4. If tsps is not satisfied, the semaphore will fall positively to one side or the other, but there is no guarantee which side will obtain the flag.



AC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range

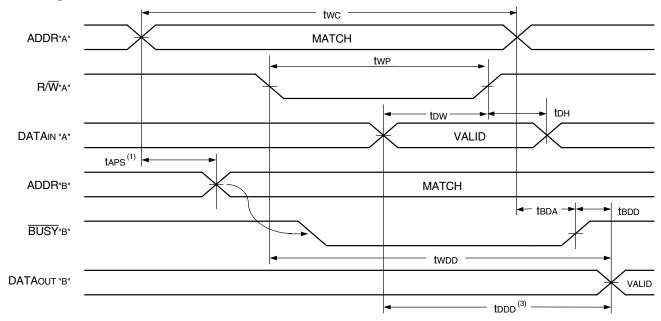
·		7038L15 Com'l Only		7038L20 Com'l & Ind					
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit			
BUSY TIMING	BUSY TIMING (M/S=Vih)								
TBAA	BUSY Access Time from Address Match		15		20	ns			
t BDA	BUSY Disable Time from Address Not Matched	_	15		20	ns			
TBAC	BUSY Access Time from Chip Enable Low	_	15		20	ns			
tBDC	BUSY Access Time from Chip Enable High	_	15	_	17	ns			
taps	Arbitration Priority Set-up Time ⁽²⁾	5	_	5	_	ns			
tBDD	BUSY Disable to Valid Data ⁽³⁾	_	15	_	17	ns			
twн	Write Hold After BUSY ⁽⁵⁾	12	_	15		ns			
BUSY TIMING	(M/S=VIL)								
twB	BUSY Input to Write ⁽⁴⁾	0	_	0		ns			
twн	Write Hold After BUSY ⁵⁾	12	_	15	_	ns			
PORT-TO-POR	PORT-TO-PORT DELAY TIMING								
twdd	Write Pulse to Data Delay ⁽¹⁾	_	30	_	45	ns			
todo	Write Data Valid to Read Data Delay ⁽¹⁾		25	_	30	ns			

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- 1. Port-to-port delay through RAM cells from writing port to reading port, refer to "Timing Waveform of Write with Port-to-Port Read and \overline{BUSY} (M/ \overline{S} = ViH)".
- 2. To ensure that the earlier of the two ports wins.
- 3. tbdd is a calculated parameter and is the greater of 0, twdd twp (actual) or tddd tdw (actual).
- 4. To ensure that the write cycle is inhibited on port "B" during contention on port "A".
- 5. To ensure that a write cycle is completed on port "B" after contention on port "A".



Timing Waveform of Write with Port-to-Port Read and **BUSY** (M/**S** = VIH)(2,4,5)

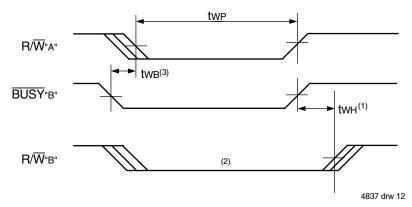


NOTES

4837 drw 11

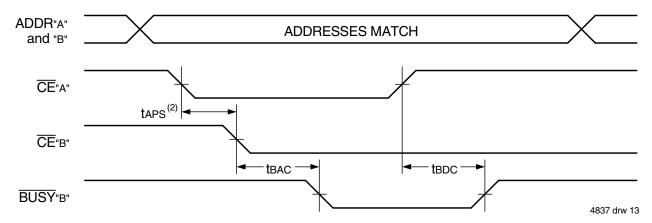
- 1. To ensure that the earlier of the two ports wins. taps is ignored for $M/\overline{S} = V_{IL}$ (SLAVE).
- 2. $\overline{CE}_L = \overline{CE}_R = V_{IL}$, refer to Chip Enable Truth Table.
- 3. $\overline{OE} = V_{IL}$ for the reading port.
- 4. If M/S = VIL (SLAVE), BUSY is an input. Then for this example BUSY "A" = VIH and BUSY "B" input is shown above.
- 5. All timing is the same for left and right ports. Port "A" may be either the left or right port. Port "B" is the port opposite from port "A".

Timing Waveform of Write with **BUSY** (M/**S** = VIL)

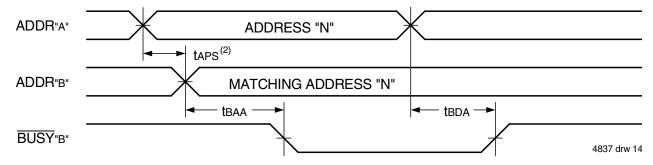


- 1. twh must be met for both $\overline{\text{BUSY}}$ input (SLAVE) and output (MASTER).
- 2. BUSY is asserted on port "B" blocking R/W"B", until BUSY"B" goes HIGH.
- 3. twb is only for the 'Slave' version.

Waveform of **BUSY** Arbitration Controlled by **CE** Timing (M/**S** = VIH)^(1,3)



Waveform of $\overline{\textbf{BUSY}}$ Arbitration Cycle Controlled by Address Match Timing (M/ $\overline{\textbf{S}}$ = VIH)⁽¹⁾



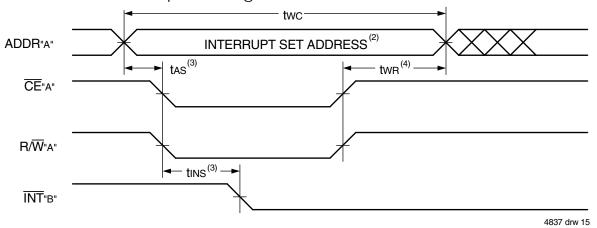
NOTES:

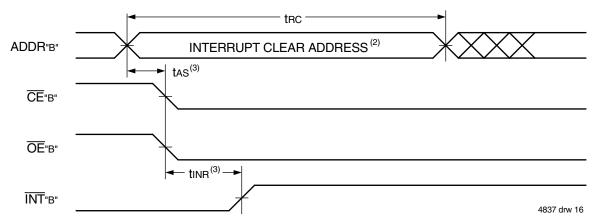
- 1. All timing is the same for left and right ports. Port "A" may be either the left or right port. Port "B" is the port opposite from port "A".
- 2. If taps is not satisfied, the BUSY signal will be asserted on one side or another but there is no guarantee on which side BUSY will be asserted.
- 3. Refer to Chip Enable Truth Table.

AC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range

		7038L15 Com'l Only		7038L20 Com'l & Ind		
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
INTERRUPT T	NTERRUPT TIMING					
tas	Address Set-up Time	0	_	0	_	ns
twr	Write Recovery Time	0	_	0	_	ns
tins	Interrupt Set Time	_	15		20	ns
tinr	Interrupt Reset Time		15		20	ns

Waveform of Interrupt Timing(1,5)





NOTES:

- 1. All timing is the same for left and right ports. Port "A" may be either the left or right port. Port "B" is the port opposite from port "A".
- 2. See Interrupt Truth Table.
- 3. Timing depends on which enable signal (CE or R/W) is asserted last.
- 4. Timing depends on which enable signal $(\overline{CE} \text{ or } R/\overline{W})$ is de-asserted first.
- 5. Refer to Chip Enable Truth Table.

Truth Table IV — Interrupt Flag^(1,4,5)

Left Port				Right Port						
R/₩L	CEL	<u>OE</u> L	A15L-A0L	ĪNT∟	R/W̄R	CER	ŌĒ R	A15R-A0R	Ī NT R	Function
L	L	Х	FFFF	Х	Х	Х	Х	Х	L ⁽²⁾	Set Right INTR Flag
Х	Х	Х	Х	Х	Х	L	L	FFFF	H ⁽³⁾	Reset Right INTR Flag
Х	Х	Х	Х	L ⁽³⁾	L	L	Х	FFFE	Х	Set Left INTL Flag
X	L	L	FFFE	H ⁽²⁾	Х	Х	Х	X	Х	Reset Left INTL Flag

NOTES:

- 1. Assumes $\overline{BUSY}L = \overline{BUSY}R = VIH$.
- 2. If $\overline{BUSY}L = VIL$, then no change.
- 3. If $\overline{\text{BUSY}}_{R} = \text{VIL}$, then no change.
- 4. INTL and INTR must be initialized at power-up.
- 5. Refer to Chip Enable Truth Table.

Truth Table V —Address **BUSY** Arbitration⁽⁴⁾

	In	puts	Out	puts	
<u>C</u> E∟	ՇĒ R	Aol-A15l Aor-A15r	BUS YL(1)	BUSY _R (1)	Function
Х	Х	NO MATCH	Н	Н	Normal
Н	Х	MATCH	Н	Н	Normal
Х	Н	MATCH	Н	Н	Normal
L	L	MATCH	(2)	(2)	Write Inhibit ⁽³⁾

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- 1. Pins BUSYL and BUSYR are both outputs when the part is configured as a master. Both are inputs when configured as a slave. BUSY outputs on the IDT7038 are push-pull, not open drain outputs. On slaves the BUSY input internally inhibits writes.
- 2. "L" if the inputs to the opposite port were stable prior to the address and enable inputs of this port. "H" if the inputs to the opposite port became stable after the address and enable inputs of this port. If taps is not met, either BUSYL or BUSYR = LOW will result. BUSYL and BUSYR outputs can not be LOW simultaneously.
- 3. Writes to the left port are internally ignored when BUSYL outputs are driving LOW regardless of actual logic level on the pin. Writes to the right port are internally ignored when BUSYR outputs are driving LOW regardless of actual logic level on the pin.
- 4. Refer to Chip Enable Truth Table.

NOTES:

Truth Table VI — Example of Semaphore Procurement Sequence (1,2,3)

Functions	Do - D17 Left	Do - D17 Right	Status
No Action	1	1	Semaphore free
Left Port Writes "0" to Semaphore	0	1	Left port has semaphore token
Right Port Writes "0" to Semaphore	0	1	No change. Right side has no write access to semaphore
Left Port Writes "1" to Semaphore	1	0	Right port obtains semaphore token
Left Port Writes "0" to Semaphore	1	0	No change. Left port has no write access to semaphore
Right Port Writes "1" to Semaphore	0	1	Left port obtains semaphore token
Left Port Writes "1" to Semaphore	1	1	Semaphore free
Right Port Writes "0" to Semaphore	1	0	Right port has semaphore token
Right Port Writes "1" to Semaphore	1	1	Semaphore free
Left Port Writes "0" to Semaphore	0	1	Left port has semaphore token
Left Port Writes "1" to Semaphore	1	1	Semaphore free

NOTES: 4837 tol 18

- 1. This table denotes a sequence of events for only one of the eight semaphores on the IDT7038.
- 2. There are eight semaphore flags written to via I/Oo and read from all I/O's (I/Oo-I/O17). These eight semaphores are addressed by Ao-A2.
- 3. $\overline{CE} = VIH$, $\overline{SEM} = VIL$ to access the semaphores. Refer to the Semaphore Read/Write Control Truth Table.

Functional Description

The IDT7038 provides two ports with separate control, address and I/O pins that permit independent access for reads or writes to any location in memory. The IDT7038 has an automatic power down feature controlled by $\overline{\text{CE}}$. The $\overline{\text{CE}}$ 0 and CE1 control the on-chip power down circuitry that permits the respective port to go into a standby mode when not selected ($\overline{\text{CE}}$ = HIGH). When a port is enabled, access to the entire memory array is permitted.

Interrupts

If the user chooses the interrupt function, a memory location (mail box or message center) is assigned to each port. The left port interrupt flag

 $(\overline{\text{INTL}})$ is asserted when the right port writes to memory location FFFE (HEX), where a write is defined as $\overline{\text{CE}}_R = R/\overline{W}_R = \text{VIL}$ per Truth Table IV. The left port clears the interrupt through access of address location FFFE when $\overline{\text{CE}}_L = \overline{\text{OE}}_L = \text{VIL}$, R/\overline{W} is a "don't care". Likewise, the right port interrupt flag ($\overline{\text{INTR}}$) is asserted when the left port writes to memory location FFFF (HEX) and to clear the interrupt flag ($\overline{\text{INTR}}$), the right port must read the memory location FFFF. The message (18 bits) at FFFE or FFFF is user-defined since it is an addressable SRAM location. If the interrupt function is not used, address locations FFFE and FFFF are not used as mail boxes, but as part of the random access memory. Refer to Table IV for the interrupt operation.

Busy Logic

Busy Logic provides a hardware indication that both ports of the RAM have accessed the same location at the same time. It also allows one of the two accesses to proceed and signals the other side that the RAM is "busy". The $\overline{\text{BUSY}}$ pin can then be used to stall the access until the operation on the other side is completed. If a write operation has been attempted from the side that receives a $\overline{\text{BUSY}}$ indication, the write signal is gated internally to prevent the write from proceeding.

The use of \overline{BUSY} logic is not required or desirable for all applications. In some cases it may be useful to logically OR the \overline{BUSY} outputs together and use any \overline{BUSY} indication as an interrupt source to flag the event of an illegal or illogical operation. If the write inhibit function of \overline{BUSY} logic is not desirable, the \overline{BUSY} logic can be disabled by placing the part in slave mode with the $\overline{M/S}$ pin. Once in slave mode the \overline{BUSY} pin operates solely as a write inhibit input pin. Normal operation can be programmed by tying the \overline{BUSY} pins HIGH. If desired, unintended write operations can be prevented to a port by tying the \overline{BUSY} pin for that port LOW.

The BUSY outputs on the IDT7038 RAM in master mode, are pushpull type outputs and do not require pull up resistors to operate. If these RAMs are being expanded in depth, then the BUSY indication for the resulting array requires the use of an external AND gate.

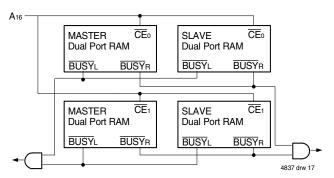


Figure 3. Busy and chip enable routing for both width and depth expansion with IDT7038 RAMs.

Width Expansion Busy Logic Master/Slave Arrays

When expanding an IDT7038 RAM array in width while using $\overline{B}USY$ logic, one master part is used to decide which side of the RAMs array will receive a $\overline{B}USY$ indication, and to output that indication. Any number of slaves to be addressed in the same address range as the master, use the $\overline{B}USY$ signal as a write inhibit signal. Thus on the IDT7038 RAM the $\overline{B}USY$ pin is an output if the part is used as a master (M/ \overline{S} pin = VIL), and the $\overline{B}USY$ pin is an input if the part used as a slave (M/ \overline{S} pin = VIL) as shown in Figure 3.

If two or more master parts were used when expanding in width, a split decision could result with one master indicating \overline{BUSY} on one side of the array and another master indicating \overline{BUSY} on one other side of the array. This would inhibit the write operations from one port for part of a word and inhibit the write operations from the other port for the other part of the word.

The \overline{BUSY} arbitration, on a master, is based on the chip enable and address signals only. It ignores whether an access is a read or write. In a master/slave array, both address and chip enable must be valid long enough for a \overline{BUSY} flag to be output from the master before the actual write pulse can be initiated with the $R\overline{W}$ signal. Failure to observe this timing can

result in a glitched internal write inhibit signal and corrupted data in the slave.

Semaphores

The IDT7038 is an extremely fast Dual-Port 64K x 18 CMOS Static RAM with an additional 8 address locations dedicated to binary semaphore flags. These flags allow either processor on the left or right side of the Dual-Port RAM to claim a privilege over the other processor for functions defined by the system designer's software. As an example, the semaphore can be used by one processor to inhibit the other from accessing a portion of the Dual-Port RAM or any other shared resource.

The Dual-Port RAM features a fast access time, and both ports are completely independent of each other. This means that the activity on the left port in no way slows the access time of the right port. Both ports are identical in function to standard CMOS Static RAM and can be read from, or written to, at the same time with the only possible conflict arising from the simultaneous writing of, or a simultaneous READ/WRITE of, a non-semaphore location. Semaphores are protected against such ambiguous situations and may be used by the system program to avoid any conflicts in the non-semaphore portion of the Dual-Port RAM. These devices have an automatic power-down feature controlled by $\overline{\text{CE}}$, the Dual-Port RAM enable, and $\overline{\text{SEM}}$, the semaphore enable. The $\overline{\text{CE}}$ and $\overline{\text{SEM}}$ pins control on-chip power down circuitry that permits the respective port to go into standby mode when not selected. This is the condition which is shown in Truth Table II where $\overline{\text{CE}}$ and $\overline{\text{SEM}}$ are both HIGH.

Systems which can best use the IDT7038 contain multiple processors or controllers and are typically very high-speed systems which are software controlled or software intensive. These systems can benefit from a performance increase offered by the IDT7038s hardware semaphores, which provide a lockout mechanism without requiring complex programming.

Software handshaking between processors offers the maximum in system flexibility by permitting shared resources to be allocated in varying configurations. The IDT7038 does not use its semaphore flags to control any resources through hardware, thus allowing the system designer total flexibility in system architecture.

An advantage of using semaphores rather than the more common methods of hardware arbitration is that wait states are never incurred in either processor. This can prove to be a major advantage in very high-speed systems.

How the Semaphore Flags Work

The semaphore logic is a set of eight latches which are independent of the Dual-Port RAM. These latches can be used to pass a flag, or token, from one port to the other to indicate that a shared resource is in use. The semaphores provide a hardware assist for a use assignment method called "Token Passing Allocation." In this method, the state of a semaphore latch is used as a token indicating that shared resource is in use. If the left processor wants to use this resource, it requests the token by setting the latch. This processor then verifies its success in setting the latch by reading it. If it was successful, it proceeds to assume control over the shared resource. If it was not successful in setting the latch, it determines that the right side processor has set the latch first, has the token and is using the shared resource. The left processor can then either repeatedly request that semaphore's status or remove its request for that semaphore to perform another task and occasionally attempt again to gain control of the token via

the set and test sequence. Once the right side has relinquished the token, the left side should succeed in gaining control.

The semaphore flags are active LOW. A token is requested by writing a zero into a semaphore latch and is released when the same side writes a one to that latch.

The eight semaphore flags reside within the IDT7038 in a separate memory space from the Dual-Port RAM. This address space is accessed by placing a LOW input on the $\overline{\text{SEM}}$ pin (which acts as a chip select for the semaphore flags) and using the other control pins (Address, $\overline{\text{CE}}$, and $\overline{\text{R/W}}$) as they would be used in accessing a standard Static RAM. Each of the flags has a unique address which can be accessed by either side through address pins A0 – A2. When accessing the semaphores, none of the other address pins has any effect.

When writing to a semaphore, only data pin Do is used. If a LOW level is written into an unused semaphore location, that flag will be set to a zero on that side and a one on the other side (see Table VI). That semaphore can now only be modified by the side showing the zero. When a one is written into the same location from the same side, the flag will be set to a one for both sides (unless a semaphore request from the other side is pending) and then can be written to by both sides. The fact that the side which is able to write a zero into a semaphore subsequently locks out writes from the other side is what makes semaphore flags useful in interprocessor communications. (A thorough discussion on the use of this feature follows shortly.) A zero written into the same location from the other side will be stored in the semaphore request latch for that side until the semaphore is freed by the first side.

When a semaphore flag is read, its value is spread into all data bits so that a flag that is a one reads as a one in all data bits and a flag containing a zero reads as all zeros. The read value is latched into one side's output register when that side's semaphore select (\overline{SEM}) and output enable (\overline{OE}) signals go active. This serves to disallow the semaphore from changing state in the middle of a read cycle due to a write cycle from the other side. Because of this latch, a repeated read of a semaphore in a test loop must cause either signal (\overline{SEM} or \overline{OE}) to go inactive or the output will never change.

A sequence WRITE/READ must be used by the semaphore in order to guarantee that no system level contention will occur. A processor requests access to shared resources by attempting to write a zero into a semaphore location. If the semaphore is already in use, the semaphore request latch will contain a zero, yet the semaphore flag will appear as one, a fact which the processor will verify by the subsequent read (see Table VI). As an example, assume a processor writes a zero to the left port at a free semaphore location. On a subsequent read, the processor will verify that it has written successfully to that location and will assume control over the resource in question. Meanwhile, if a processor on the right side attempts to write a zero to the same semaphore flag it will fail, as will be verified by the fact that a one will be read from that semaphore on the right

side during subsequent read. Had a sequence of READ/WRITE been used instead, system contention problems could have occurred during the gap between the read and write cycles.

It is important to note that a failed semaphore request must be followed by either repeated reads or by writing a one into the same location. The reason for this is easily understood by looking at the simple logic diagram of the semaphore flag in Figure 4. Two semaphore request latches feed into a semaphore flag. Whichever latch is first to present a zero to the semaphore flag will force its side of the semaphore flag LOW and the other side HIGH. This condition will continue until a one is written to the same semaphore request latch. Should the other side's semaphore request latch have been written to a zero in the meantime, the semaphore flag will flip

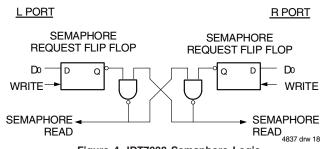


Figure 4. IDT7038 Semaphore Logic

over to the other side as soon as a one is written into the first side's request latch. The second side's flag will now stay LOW until its semaphore request latch is written to a one. From this it is easy to understand that, if a semaphore is requested and the processor which requested it no longer needs the resource, the entire system can hang up until a one is written into that semaphore request latch.

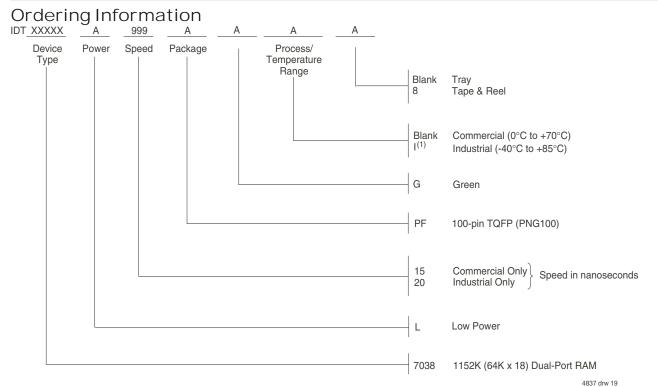
The critical case of semaphore timing is when both sides request a single token by attempting to write a zero into it at the same time. The semaphore logic is specially designed to resolve this problem. If simultaneous requests are made, the logic guarantees that only one side receives the token. If one side is earlier than the other in making the request, the first side to make the request will receive the token. If both requests arrive at the same time, the assignment will be arbitrarily made to one port or the other.

One caution that should be noted when using semaphores is that semaphores alone do not guarantee that access to a resource is secure. As with any powerful programming technique, if semaphores are misused or misinterpreted, a software error can easily happen.

Initialization of the semaphores is not automatic and must be handled via the initialization program at power-up. Since any semaphore request flag which contains a zero must be reset to a one, all semaphores on both sides should have a one written into them at initialization from both sides to assure that they will be free when needed.



Industrial and Commercial Temperature Ranges



NOTES:

- Industrial temperature range is available.
 For specific speeds, packages and powers contact your sales office.
- LEAD FINISH (SnPb) parts are Obsolete. Product Discontinuation Notice PDN# SP-17-02
 Note that information regarding recently obsoleted parts is included in this datasheet for customer convenience

Orderable Part Information

Speed (ns)	Orderable Part ID	Pkg. Code	Pkg. Type	Temp. Grade
15	7038L15PFG	PNG100	TQFP	С
	7038L15PFG8	PNG100	TQFP	С
20	7038L20PFGI	PNG100	TQFP	I
	7038L20PFGl8	PNG100	TQFP	I

Industrial and Commercial Temperature Ranges

Datasheet Document History

09/30/99: Initial Public Release 11/10/99: Replaced IDT logo

01/12/01: Page 3 Increased storage temperature parameter

Clarified TA parameter

Page 5 DC Electrical parameters-changed wording from open to disabled

Page 14 Added IV to Truth Table in "Interrupt" paragraph

Changed ±200mV to 0mV in notes

Removed Preliminary status

11/19/01: Page 2 Added date revision for pin configuration

Pages 3, 5, 7, 10 & 12 Removed Industrial temp footnote from all tables

Pages 5, 7, 10 & 12 Added Industrial temp for 20ns speed to DC and AC Electrical Characteristics

Page 17 Added Industrial temp offering to 20ns ordering information

Pages 1 & 17 Replaced TM logo with ® logo

01/29/09: Page 17 Removed "IDT" from orderable part number

02/05/15: Page 1 Added green availability to features

Page 2 Removed IDT in reference to fabrication

Page 17 Added Green and Tape & Reel indicators to ordering information

Page 2 & 17The package code PN100-1 changed to PN100 to match standard package codes

Page 15 & 16 Corrected some text typos

06/08/18: Product Discontinuation Notice - PDN# SP-17-02

Last time buy expires June 15, 2018

06/11/19: Page 1 & 17 Updated Commercial speed grade offering in Features & Ordering Information

Page 2 Changed diagram for the PNG100 pin configuration by rotating package pin labels and pin numbers

90 degrees counter clockwise to reflect pin 1 orientation and added pin 1 dot at pin 1

Aligned the top and bottom pin labels in the standard direction

Added IDT logo to the PNG100 pin configuration and changed the text to be in alignment with the new diagram marking specs

Updated footnote reference for PNG100

Page 2 & 17 The package code PN100 changed to PNG100 to match standard package code

Page 17 Revised LEAD FINISH note to indicate Obsolete

Page 17 Added Orderable Part Information

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(Rev.1.0 Mar 2020)

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IS66WVE2M16ECLL-70BLI IS66WVE4M16EALL-70BLI IS61WV102416DBLL-10TLI CY7C1381KV33-100AXC CY7C1381KVE33133AXI 8602501XA 5962-3829425MUA 5962-3829430MUA 5962-8866201YA 5962-8866204TA 5962-9062007MXA 59629161705MXA GS882Z18CD-150I 8413202RA 5962-8866203YA IS61WV102416DBLL-10BLI CY7C1380KV33-250AXC AS6C801655BINTR GS81284Z18B-250I AS7C34096B-10TIN GS84018CB-200I IS62WV25616EALL-55TLI IS61WV204816BLL-10TLI
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